

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) A multi-chip module system comprising:
a substrate having at least a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat and having at least one other vacant position having, in turn, a predetermined configuration for locating a second semiconductor device thereat on the multi-chip module system; and
a first semiconductor device located in the at least first position of the substrate for use in ~~said~~the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic.
2. (Amended) The multi-chip module system of claim 1, further comprising:
the at least one other vacant position having ~~at~~the predetermined configuration for locating ~~at~~the second semiconductor device thereat which is substantially the same as the first semiconductor device.
3. (Amended) The multi-chip module system of claim 1, further comprising:
the at least one other vacant position having ~~at~~the predetermined configuration for locating ~~at~~the second semiconductor device thereat; and
~~at~~the second semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.
4. (Amended) The multi-chip module system of claim 1, further comprising:
the at least one other vacant position having ~~at~~the predetermined configuration for locating ~~at~~the second semiconductor device thereat; and
~~at~~the second semiconductor device having a second predetermined performance characteristic of at least substantially twice ~~to~~ that of the first predetermined performance characteristic of the first semiconductor device.

5. (Amended) A multi-chip module system comprising:
a substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, and having at least one other vacant position having, in turn, a predetermined configuration for locating a third semiconductor device thereat on the multi-chip module system;
atthe first semiconductor device located in the first position of the substrate for use in saidthe multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
atthe second semiconductor device located in the second position of the substrate for use in saidthe multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

6. (Amended) The multi-chip module system of claim 4, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third semiconductor device thereat which is substantially the same as the first semiconductor device.

7. (Amended) The multi-chip module system of claim 4, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third semiconductor device thereat; and
atthe third semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

8. (Amended) The multi-chip module system of claim 4, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third
semiconductor device thereat; and
~~at~~ the third semiconductor device having a predetermined performance characteristic of at least
substantially twice ~~to~~ that of the first predetermined performance characteristic of the
first semiconductor device.

9. (Amended) The multi-chip module system of claim 4, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third
semiconductor device thereat; and
~~at~~ the third semiconductor device having a predetermined performance characteristic of at least
substantially three times greater than that of the second predetermined performance
characteristic of the second semiconductor device.

10. (Amended) The multi-chip module system of claim 4, further comprising:
the at least one other vacant position having a predetermined configuration for locating a third
semiconductor device thereat; and
~~at~~ the third semiconductor device having a predetermined performance characteristic of at least
substantially four times greater than that of the first and the second predetermined
performance characteristic of the first semiconductor device and the second
semiconductor device combined.

16. (Amended) The multi-chip module system of claim 4, further comprising:
a third semiconductor device; and
an adapter connected to the third semiconductor device, the adapter having a configuration for
connecting the adapter to the at least one other vacant position on the substrate to
connect the third semiconductor device to the substrate.

20. (Amended) The multi-chip module system of claim 19, further comprising:
the at least one other vacant predetermined configuration position for locating athe second
semiconductor device thereat which is substantially the same as the first semiconductor
device.

21. (Amended) The multi-chip module system of claim 19, further comprising:
the at least one other vacant predetermined configuration position having a predetermined
configuration for locating athe second semiconductor device thereat; and
athe second semiconductor device having a predetermined performance characteristic
substantially similar to that of the first predetermined performance characteristic of the
first semiconductor device.

22. (Amended) The multi-chip module system of claim 19, further comprising:
the at least one other vacant predetermined configuration position having a predetermined
configuration for locating athe second semiconductor device thereat; and
athe second semiconductor device having a predetermined performance characteristic of at
least substantially twice ~~to~~ that of the first predetermined performance characteristic of
the first semiconductor device.

23. (Amended) A multi-chip module system comprising:
a substrate having a first predetermined configuration position for locating a first
semiconductor device thereat, having a second predetermined configuration position for
locating a second semiconductor device thereat, and having at least one other vacant
predetermined configuration position for locating a third semiconductor device thereat
on the multi-chip module system;
athe first semiconductor device located in the first predetermined configuration position of the
substrate for use in ~~said~~the multi-chip module system, the first semiconductor device
having a first predetermined performance characteristic; and

at the second semiconductor device located in the second predetermined configuration position of the substrate for use in said the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

24. (Amended) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration ~~vacant~~ position for locating at the third semiconductor device thereat which is substantially the same as the first semiconductor device.

25. (Amended) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating at the third semiconductor device thereat; and
at the third semiconductor device having a third predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

26. (Amended) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating at the third semiconductor device thereat; and
at the third semiconductor device having a third predetermined performance characteristic of at least substantially twice ~~to~~ that of the first predetermined performance characteristic of the first semiconductor device.

27. (Amended) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating at the third semiconductor device thereat; and
at the third semiconductor device having a third predetermined performance characteristic of at least substantially three times greater than that of the second predetermined

performance characteristic of the second semiconductor device.

28. (Amended) The multi-chip module system of claim 23, further comprising:
the at least one other vacant predetermined configuration position for locating a third
semiconductor device thereat; and
a the third semiconductor device having a third predetermined performance characteristic of at
least substantially four times greater than that of the first and second predetermined
performance characteristic of the first semiconductor device and the second
semiconductor device combined.

34. (Amended) The multi-chip module system of claim 23, further comprising:
~~a third semiconductor device; and~~
an adapter connected to the third semiconductor device, the adapter for connecting the adapter
to the at least one other vacant predetermined configuration position on the substrate to
connect the third semiconductor device to the substrate.

35. (Amended) A multi-chip module system comprising:
a substrate having a first predetermined configuration position for locating a first
semiconductor device thereat, having a second predetermined configuration position for
locating a second semiconductor device thereat, having a first vacant predetermined
configuration position for locating a third semiconductor device thereat, and having a
second vacant predetermined configuration for locating a fourth semiconductor device
thereat on the multi-chip module system;
a the first semiconductor device located in the first predetermined configuration position of the
substrate for use in ~~said~~ the multi-chip module system, the first semiconductor device
having a first predetermined performance characteristic; and
a the second semiconductor device located in the second predetermined configuration position
of the substrate for use in ~~said~~ the multi-chip module system, the second semiconductor

device having a second predetermined performance characteristic.

36. (Amended) The multi-chip module of claim 35, wherein:
the first vacant predetermined ~~performance~~configuration position located on the substrate is
located on one side of the substrate; and
the second vacant predetermined ~~performance~~configuration position located on the substrate is
located on the other side of the substrate.